



Final Product Change Notification

201810025F01

Issue Date: 18-Nov-2018

Effective Date: 16-Feb-2019

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online



QUALITY

Management Summary

Completion of MST Final Test Platform expansion / relocation from the NXP ATTJ Tianjin, China test site to the KESM Industries Tianjin, China test site for supply assurance.

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

MST Final Test Platform Expansion / Relocation from ATTJ to KESM - Completion

Description of Change

Previously NXP Semiconductors announced with PCN 201704014F01 from April 2017, the first phase of the MST Final Test platform expansion / relocation from the NXP ATTJ Tianjin, China test site to the KESM Industries Tianjin, China test site. Additional floor space was required at the ATTJ site for newer / more complex test platforms and resulted in the relocation of the legacy MST test platform and associated hardware to KESM.

NXP Semiconductors now announces with this PCN 201810025F01 the completion of this expansion / relocation for the remaining products. So, this is a completion of the previously announced test site expansion, for the remaining products that were not included in the first phase. Most customers already have approved the first phase activity, as announced in PCN 201704014F01.

Please see the attached qualification results and change summary for additional details.

Reason for Change

Qualification of KESM Industries Tianjin, China is required for customer supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not applicable

Production

Planned first shipment 16-Feb-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
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201704014F01	30-Apr-2017	14-Jun-2017	MST Final Test Platform Expansion / Relocation from ATTJ to KESM
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Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 18-Dec-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Affected Part Numbers

MC33662BLEF

MC33660BEFR2

MC33660BEF

MC33897CTEFR2

MCZ33897TEFR2

MC33897CTEF

MC33662LEF